

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN mm (inches)
PER ANSI Y14.5M-1982.

TOLERANCES ARE:
DECIMAL ANGLE
.XX ±.12 (.005) ±1/2°
.XXX ±.05 (.002)

MATERIAL(S):
See Notes

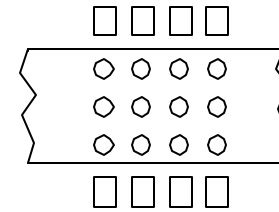
FINISH:
See Notes

Notes:

1. Base Metal - Copper D119 194
2. Lead Finish
Basic PN - Sn/Pb Sn =>80%
Z option - 100% Matte Sn - .01 (.0004) thk min
3. Devices may be received with either backside pattern shown above.

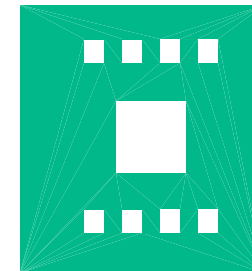
- Do Not Scale Hard Copy -

Caution: The Land Patterns and Solder Mask shown are generic for this package. Refer to product data sheet for any required variations specific to an application.



Scale 4:1

- Generic Land Pattern -
Land Pattern is applicable to both bottom side styles.



Scale 4:1

- Generic Solder Mask Opening -
Solder mask opening is applicable to both bottom side styles.



Package Type:

SOIC-8 with EPAD

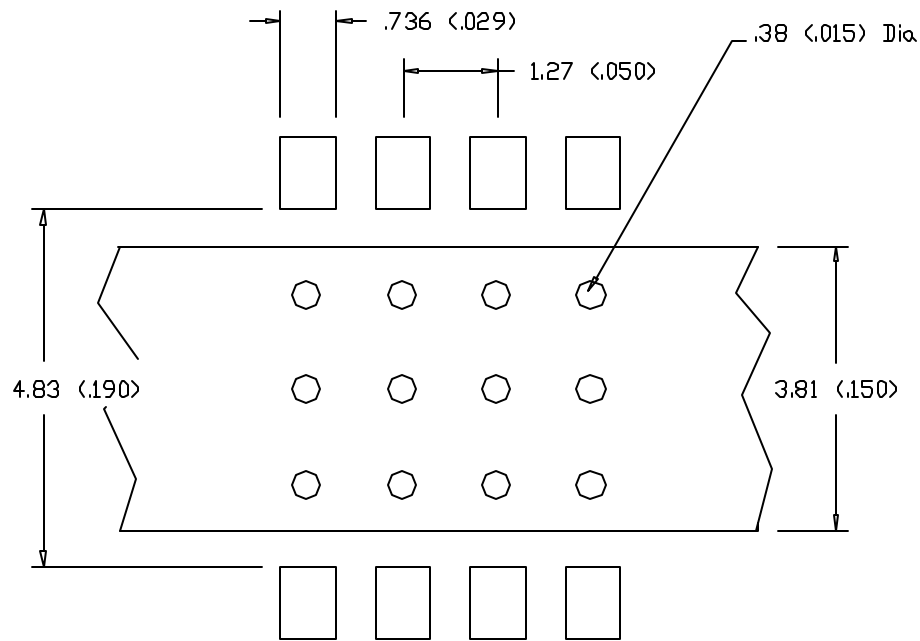
SMDI Package Type: XXX-XX18

Ref Dwg No.

MPO-101644

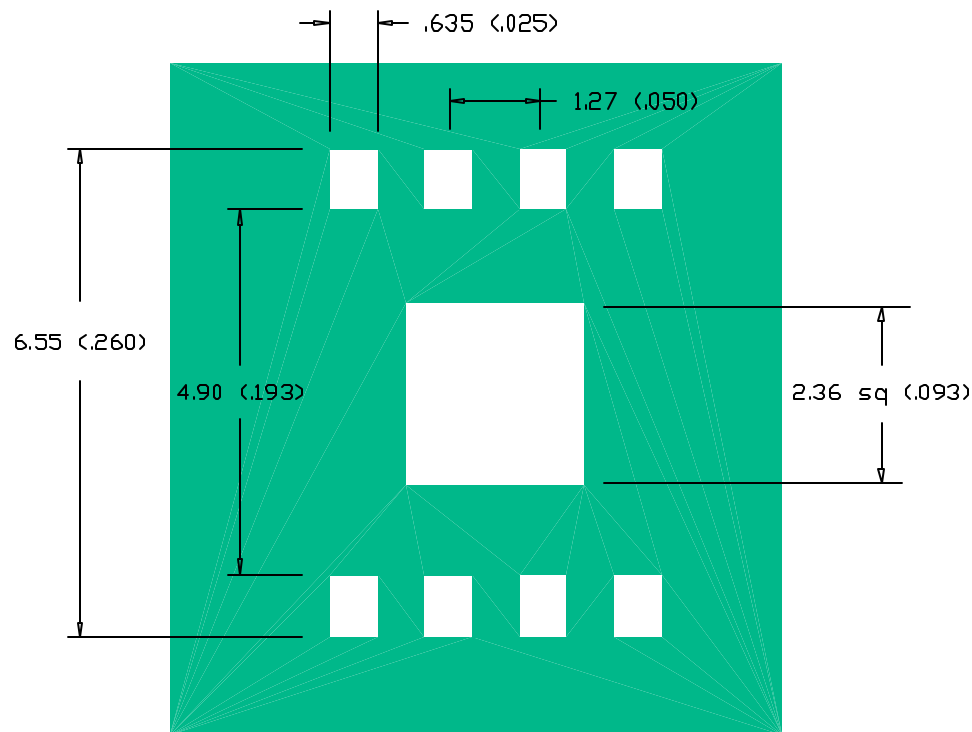
Sht 1 of 2

REV
E



Scale 10:1

- Generic Land Pattern -
Land Pattern is applicable to both bottom side styles.



Scale 10:1

- Generic Solder Mask Opening -
Solder mask opening is applicable to both bottom side styles.

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MATERIAL(S):

See Notes

FINISH:

See Notes

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Package Type:		
SOIC-8 with EPAD		
SMDI Package Type: XXX-XX18		
Ref Dwg No.	MP0-101644	Sht 2 of 2
		REV E